

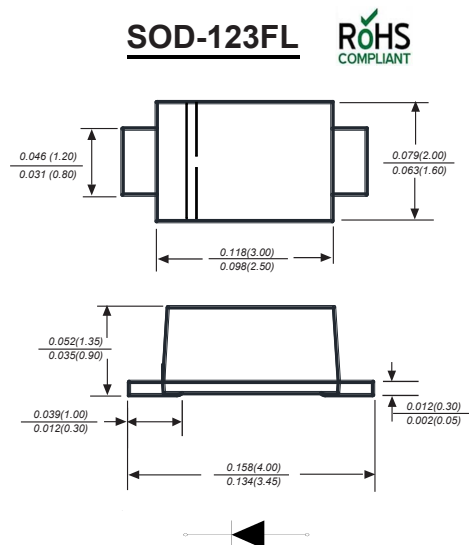
SURFACE MOUNT SUPER FAST RECTIFIER

Features

- ◆ Glass passivated device
- ◆ Ideal for surface mouted applications
- ◆ Low reverse leakage
- ◆ Metallurgically bonded construction
- ◆ High temperature soldering guaranteed:
250°C/10 seconds,0.375"(9.5mm) lead length,
5 lbs. (2.3kg) tension

Mechanical Data

Case : JEDEC SOD-123FL molded plastic body
 Terminals : Solderable per MIL-STD-750,Method 2026
 Polarity : Polarity symbol marking on body
 Mounting Position : Any
 Weight : 0.00053 ounce, 0.015grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

Parameter	SYMBOLS	DSF1A	DSF1B	DSF1C	DSF1D	DSF1E	DSF1G	DSF1J	UNITS
Marking Code		E1A	E1B	E1C	E1D	E1E	E1G	E1J	
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V _{RMS}	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	V _{DC}	50	100	150	200	300	400	600	V
Maximum average forward rectified current at TL(see fig.1)	I _{AV}	1.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	30							A
Maximum instantaneous forward voltage at 1.0A	V _F	1				1.25		1.68	V
Maximum DC reverse current TA=25℃ at rated DC blocking voltage TA=125℃	I _R	5 100							μA
Typical junction capacitance (NOTE 1)	C _J	15							pF
Maximum Reverse Recovery Time (NOTE 2)	t _{rr}	35							ns
Typical thermal resistance (NOTE 3)	RθJA	85							℃/W
Operating junction temperature range	T _J	-55 to +150							℃
Storage temperature range	T _{STG}	-55 to +150							℃

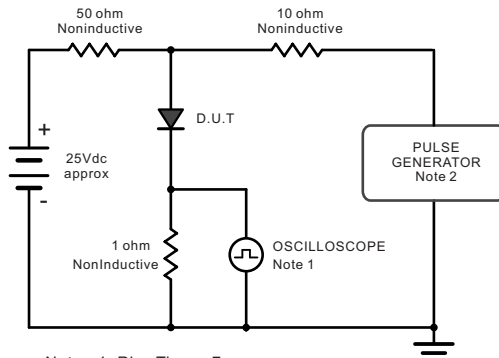
Note: 1.Measured with $I_F=0.5A$, $I_R=1A$, $I_{rr}=0.25A$.

2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

3.PCB mounted on 2.0*2.0" (5.0*5.0cm) copper pad area.

Typical Characteristics

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm, 22pF.
2. Rise Time = 10ns, max.
Source Impedance = 50 ohms.

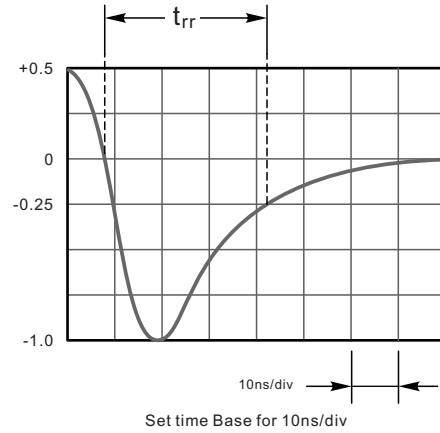


Fig.2 Maximum Average Forward Current Rating

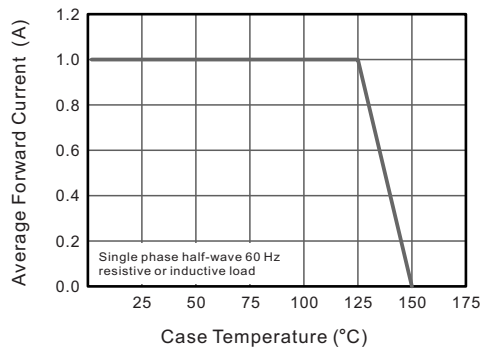


Fig.3 Typical Reverse Characteristics

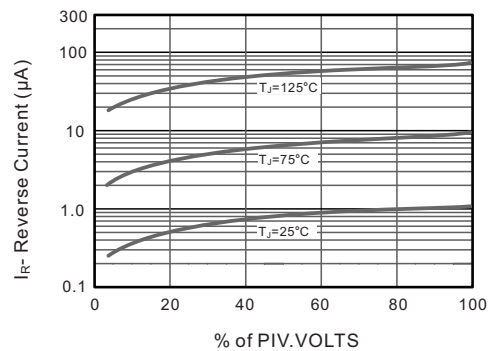


Fig.4 Typical Forward Characteristics

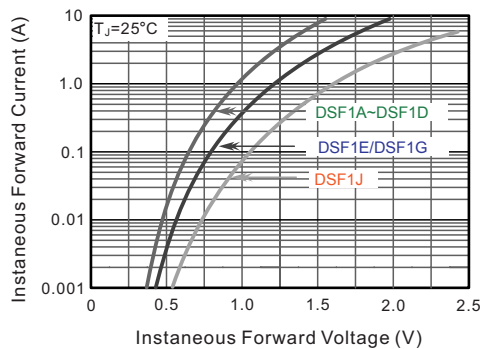


Fig.5 Typical Junction Capacitance

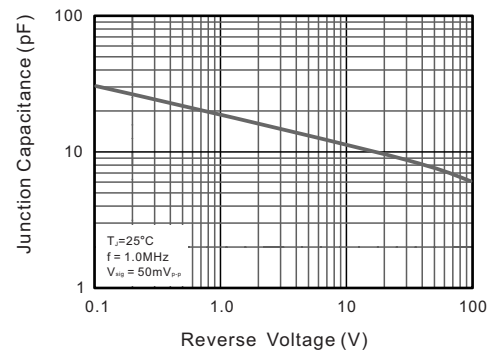
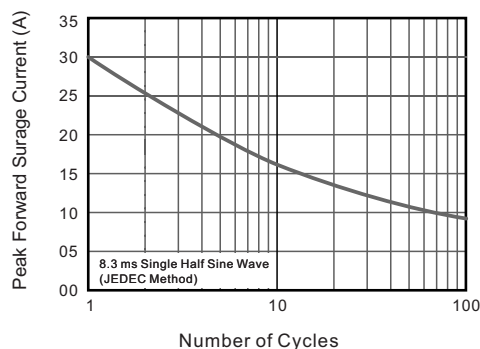
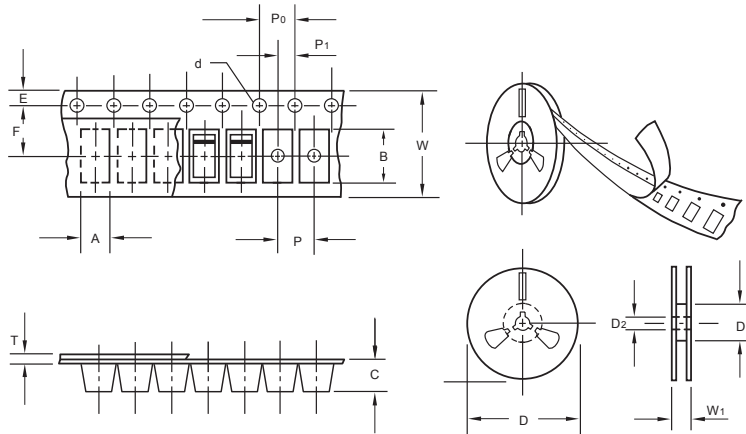


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current



The curve above is for reference only.

Packing information



unit:mm

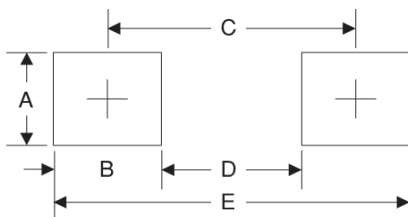
Item	Symbol	Tolerance	SOD-123FL
Carrier width	A	0.1	2.1
Carrier length	B	0.1	4.0
Carrier depth	C	0.1	1.60
Sprocket hole	d	0.05	1.55
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	50.0
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	8.15
Reel width	W1	1.0	10.5

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)
SOD-123FL	7"	3,000	4.0	45,000	190*190*190	178	400*400*220	180,000

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.2	0.047
B	1.2	0.047
C	3.2	0.126
D	2	0.079
E	4.4	0.173

Important Notice and Disclaimer

Microdiode Electronics (Shenzhen) reserves the right to make changes to this document and its products and specifications at any time without notice. Customers should obtain and confirm the latest product information and specifications before final design, purchase or use.

Microdiode Electronics (Shenzhen) makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Microdiode Electronics (Shenzhen) assume any liability for application assistance or customer product design. Microdiode Electronics (Shenzhen) does not warrant or accept any liability with products which are purchased or used for any unintended or unauthorized application.

No license is granted by implication or otherwise under any intellectual property rights of Microdiode Electronics (Shenzhen).

Microdiode Electronics (Shenzhen) products are not authorized for use as critical components in life support devices or systems without express written approval of Microdiode Electronics (Shenzhen).